

PRODUCT NUMBER

98423-XXX-XXXLF

PLATING

S = 0.38µm GOLD/GXT
ON CONTACT AREA
2µm MIN MATTE
TIN ON TAIL

G = 0.76µm GOLD/GXT
ON CONTACT AREA
2µm MIN MATTE
TIN ON TAIL

F = GOLD FASH
ON CONTACT AREA
2µm MIN MATTE

RoHS COMPATIBLE, SEE NOTE 6

PACKAGING OPTIONAL LETTER (SEE NOTE 5)

NB OF POSITIONS PER ROW
02 TO 25 POS

PIN STYLE	MATING STYLE	SOLDER STYLE
61	4.00	2.50
62	7.00	3.00
63	7.00	3.50

NOTES:

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK
2. MATERIAL TERMINAL: COPPER ALLOY
3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.
5. PACKAGING:

= PLASTIC BOX

U = TUBE AVAILABLE FROM 06 TO 50 POS

6. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

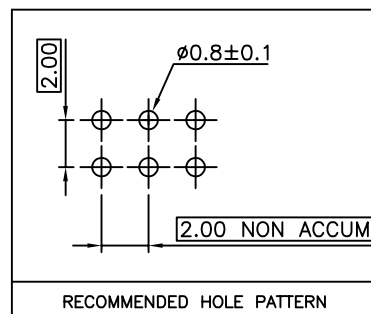
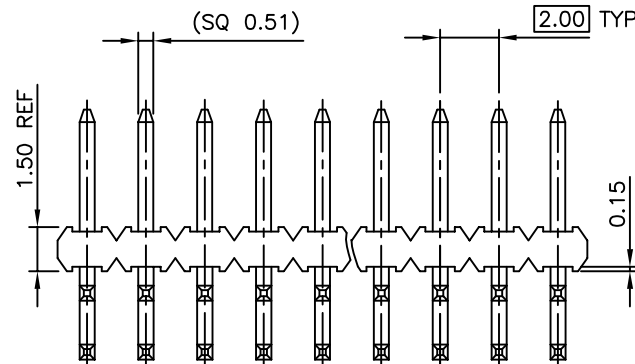
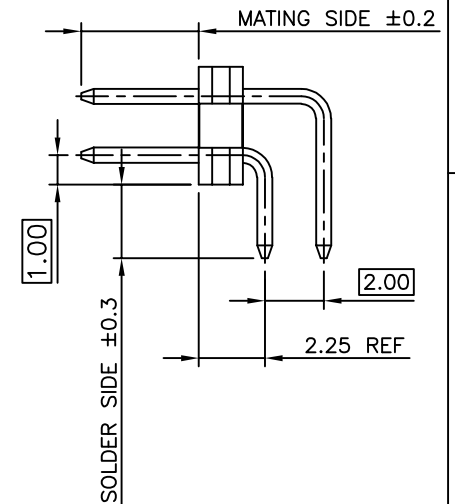
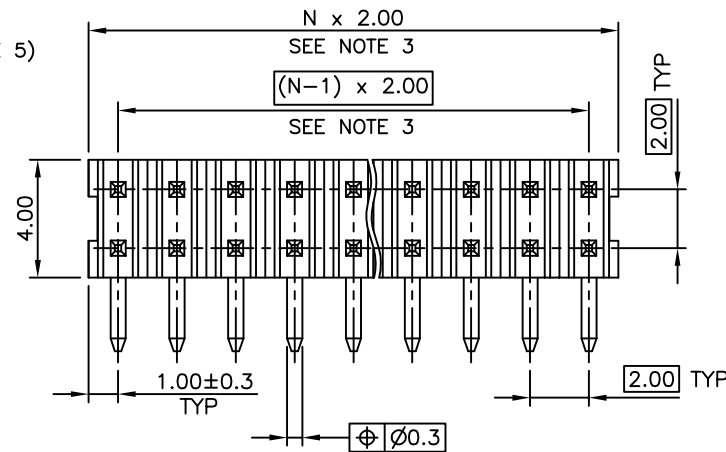
- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C ±5°C SOLDER BATH TEMPERATURE FOR
5 SECONDS IN A WAVE SOLDER APPLICATION
WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELLING:

- MEETS PACKAGING SPECS AS PER GS-14-920
- THIS PRODUCT MEETS EUROPEAN DIRECTIVES
AND OTHER COUNTRY REGULATIONS AS DISCRIBED
IN GS-47-0004



mat'l. code		surface	tolerance	projection	product family
		ISO 1302	ISO 406	ISO 101	MINITEK
ltr	ecn no	dr	date	tolerances unless otherwise specified	title
A	F10338	LMU	03.10.01	angles	X ±0.3
B	F04-0351	JCO	05.01.13	linear	X.X ±0.13
C	F06-0210	LMU	06.07.05		X.XX ±0.05
D	F08-0145	ELA	17.04.08	dr	L MULIN 04.09.28
E	B-19190	LMU	14.10.24	engr	J COMPAGNON 04.09.28
F	F-25393	DDE	16.11.21	chr	
G	F-26943	DDE	17.05.10	appd	JM.C 04.09.28
sheet	revision				
index	sheet				



UNSHR HEADER
RIGHT ANGLE TMT

dwg no 98423 sheet 1 of 1 size A3

type CUSTOMER Drawing